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HARDWARE NAME: MAX17570C_MAX17570F_EVKIT_A

HARDWARE NUMBER:

ENGINEER:

DESIGNER:

DATE: 03/1/2023

ODB++/GERBER: ASSEMBLY_BOTTOM

MH3

MH2

MH4

MH1

(LAYER 1) TOP SIDE OF PCB BOARD
BOTTOM SIDE

REFDES: MH2, MH1, MH4, MH3

STANDOFF ASSEMBLY